

**Amendments to the Specification:**

Please replace the paragraph beginning on line 13 of page 20 with the following amended paragraph:

The top mask structure is illustrated in Fig. 24. In this version the entire stack 2401 is deposited on a substrate 2402 coated with a conductor 2403, which may be a transparent conductor 2403. Passivation layer 2404 is applied and a window 2405 is etched to define the active area 2406. The transparent conductive layer 2407 is applied over the window, overlapping the ~~passivation transparent-conductive~~ layer 2404. Although there may still be a step for the metal line-out 2408 at the edge of the transparent conductive layer 2407, this is not problematic because it is a conductor-conductor contact and the contact made at the base of the transparent conductive layer 2407 structure will be sufficient.